

PCB LAYOUT * - COMPONENT VIEW

TECHNICAL CHARACTERISTICS

MATERIAL
 INSULATOR: LCP
 FLAMABILITY RATING: UL94-V0
 COLOR: BLUE
 CONTACT MATERIAL: PHOSPHORE BRONZE
 CONTACT TYPE: STAMPED
 CONTACT PLATING: UNDERPLATE 1.27 to 2.54 µm Ni
 CONTACT AREA 0.76 µm Gold
 SOLDER TAIL AREA 2.54 to 5.08 µm Matt Tin
 SHIELDING: BRASS MATT TIN PLATED

ENVIRONMENTAL
 OPERATING TEMPERATURE: -20 up to +85°C
 COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC
 HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

ELECTRICAL
 CURRENT RATING:
 - PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max
 - OTHER PINS 0.25 A Max
 WORKING VOLTAGE: 30Vac
 DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min
 INSULATION RESISTANCE: > 100MΩ
 CONTACT RESISTANCE:
 - PIN 1 & PIN 4: 30mΩ Max
 - OTHER PINS: 50mΩ Max

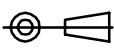

STANDARD
 CERTIFIED: E323964 / MODEL NUMBER 692122030100

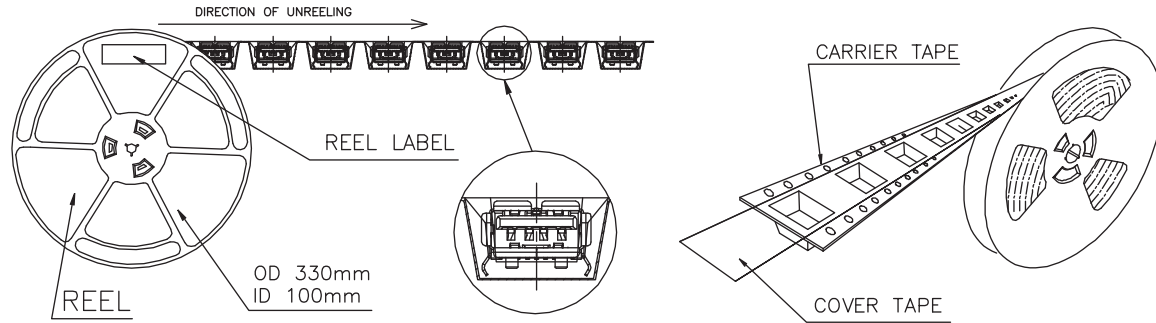
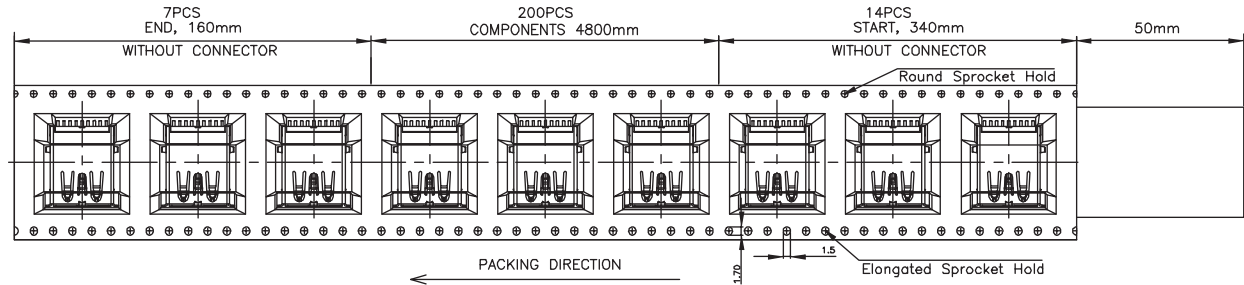
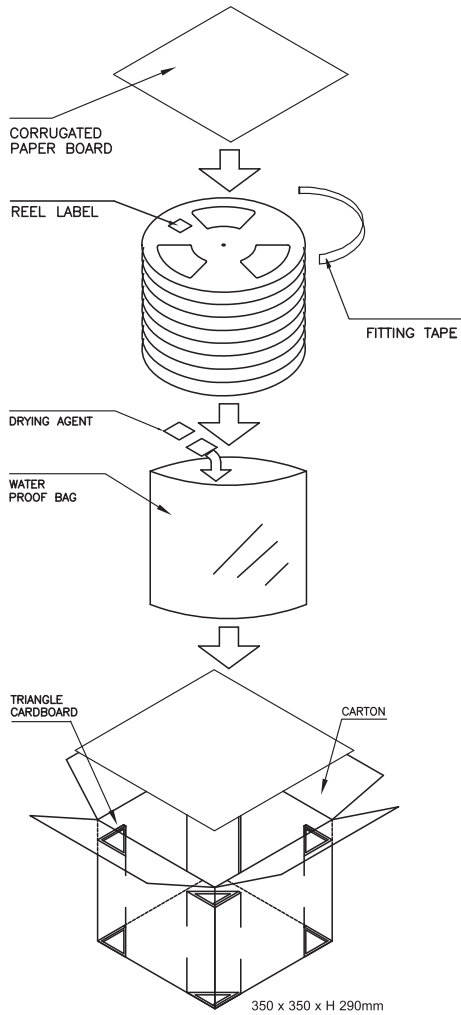
MECHANICAL
 INSERTION FORCE: 35.0N Max
 EXTRACTION FORCE: 10.0N min
 QUALITY CLASS: 5000 MATING CYCLES

SOLDERING
 REFLOW PROCESS AS PER JEDEC J-STD-020D

PACKAGING
 TAPE & REEL

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

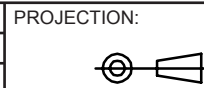
RoHS Compliant				PROJECTION: 	GENERAL TOLERANCE .X = +/- 0.2 .XX = +/- 0.15		DESCRIPTION: USB 3.0 HORIZONTAL TYPE A	SIZE A4
G	01-APR-14	SOLDERING	QL					
F	17-SEP-13	CHARACTERISTICS	QL	SCALE:				
E	10-SEP-13	DIM UPDATE	QL		SHEET: 1/3			
D	09-NOV-11	STENCIL	GG		DRAW: JOE			
C	21-SEP-11	NOTE	GG					
B	10-MAY-11	UL	GG					
A	04-AUG-10	PDF	JP					
REV	DATE	FILE	BY					



NOTES

1. MATERIALS: PS
 2. 1000PCS/CARTON
 3. RoHS
- All Material in According With The Rohs Environment Related Substances List Controlled.

RoHS Compliant			
G			
F			
E			
D			
C			
B			
A			
REV	DATE	FILE	BY



GENERAL TOLERANCE

.X = ± 0.2

.XX = ± 0.15



APPROVAL: RJ

UNIT: MM

SCALE:

SHEET: 2/3

DRAW: JOE

DESCRIPTION: USB 3.0 HORIZONTAL TYPE A

WERI PART NO: 692 122 030 100

SIZE

A4

1

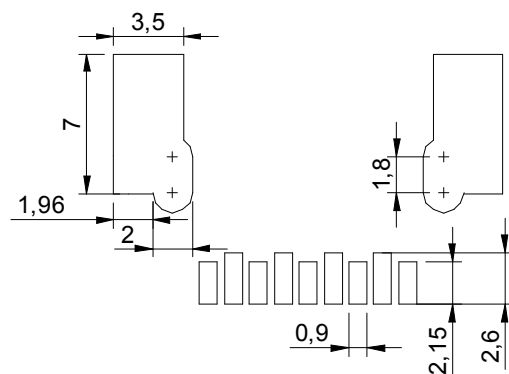
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3

4

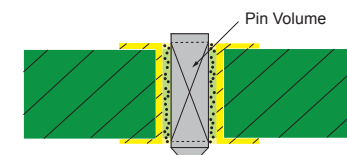
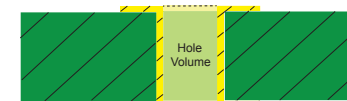
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Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT * - COMPONENT VIEW

PCB cross section



Free volume for solder paste

Theoretical Formula for Through Hole pins

Volume of the stencil aperture = (Hole volume - Pin volume) x 2

or

Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil

Stencil Thickness: 150 µm

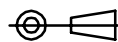
PCB

PCB thickness: 1.6mm

RoHS Compliant

* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS

PROJECTION:



GENERAL TOLERANCE

.X = +/- 0.2

.XX = +/- 0.15



APPROVAL: RJ

UNIT: MM

DESCRIPTION: USB 3.0 HORIZONTAL TYPE A

SIZE

SCALE:

SHEET: 3/3

WERI PART NO: 692 122 030 100

A4

REV	DATE	FILE	BY

DRAW: JOE